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(54) Title: LED PHOSPHOR DEPOSITION

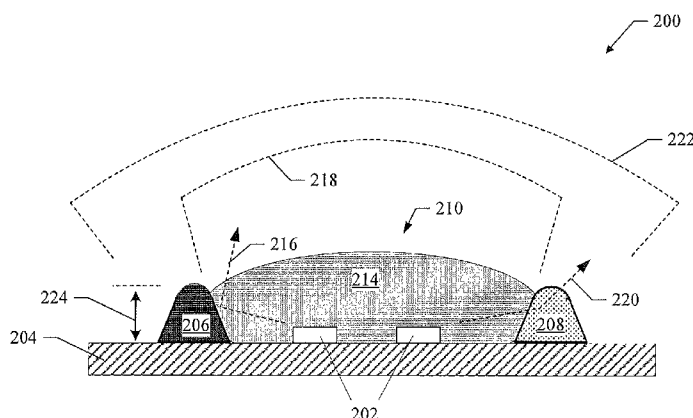


FIG. 2

(57) Abstract: LED phosphor deposition for use with LEDs. In an aspect, a method is provided for forming an encapsulation. The method includes determining a geometric shape for the encapsulation, selecting a dam material, applying the dam material to a substrate to form a boundary defining a region having the geometric shape, and filling the region with encapsulation material to form the encapsulation. In another aspect, an LED apparatus is provided that includes at least one LED chip and an encapsulation disposed on the at least one LED chip. The encapsulation is formed by determining a geometric shape for the encapsulation, selecting a dam material, applying the dam material to a substrate to form a boundary defining a region having the geometric shape, and filling the region with encapsulation material to form the encapsulation.